

9. The method for manufacturing semiconductor devices of claim 8, wherein the specified amount of resin is an amount of resin that fills about one half of the cavity.

10. The method for manufacturing semiconductor devices of claim 8, further comprising:

forcing the resin into the cavity using a plunger; and
detecting a position of the plunger to determine when the specified amount of resin has been supplied to the cavity.

11. The method for manufacturing semiconductor devices of claim 8, further comprising:

forcing the resin into the cavity using a plunger; and
detecting an amount of time the plunger is driven to determine when the specified amount of resin has been supplied to the cavity.

12. The method for manufacturing semiconductor devices of claim 8, wherein the specified amount of resin is an amount of resin that is supplied to the cavity without hardening.

13. The method of transfer molding comprising:
placing a package into a cavity of a resin mold;

forcing resin into the cavity of the resin mold; and
adjusting air pressure in the cavity based on an amount of the resin forced into
the cavity.

14. The method of transfer molding of claim 13, wherein said forcing comprises
supplying resin from a transfer pot to the cavity using a plunger.

15. The method of transfer molding of claim 14, further comprising:
detecting a position of the plunger to determine the amount of resin forced into
the cavity.

16. The method of transfer molding of claim 14, further comprising:
detecting an amount of time the plunger is driven to determine the amount of
resin forced into the cavity.

17. The method of transfer molding of claim 13, wherein said adjusting air
pressure comprises reducing the air pressure in the cavity when a specified amount of
resin is forced into the cavity.

18. The method of transfer molding of claim 17, wherein the specified amount of
resin is one half an amount of resin that would fill the cavity.

19. The method of transfer molding of claim 17, wherein the specified amount of resin is an amount of resin that is supplied to the cavity without hardening.

20. The method of transfer molding of claim 13, wherein said adjusting air pressure comprises extracting air from the cavity.

21. The method of transfer molding of claim 13, wherein the resin mold comprises a plurality of cavities that are interconnected, and said adjusting air pressure comprises adjusting air pressure in each of the plurality of cavities based on an amount of resin forced into the plurality of cavities.--

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